

6. A semiconductor physical quantity sensor comprising:
 a semiconductor chip placed on at least one of a resin case and a substrate via a pedestal, and
 wherein both first pads in said semiconductor chip which are to be pulled down and a ground pad are
 electrically connected to a ground outside said semiconductor chip.

7. The semiconductor physical quantity sensor according to Claim 6, wherein characterized in that both
 second pads in said semiconductor chip which are to be pulled up and a power supply pad are electrically
 connected to a power supply outside said semiconductor chip

8. A semiconductor physical quantity sensor comprising:
 a semiconductor chip placed on at least one of a resin case and a substrate via a pedestal, and
 wherein both second pads in said semiconductor chip which are to be pulled up and a power supply pad
 are electrically connected to a power supply outside said semiconductor chip.

9. A semiconductor physical quantity sensor comprising:
 a semiconductor chip placed on a resin case via a pedestal, said resin case including lead frames that are
 insert-molded, and within said resin case are formed both a ground-connecting external wire through which a
 ground pad of said semiconductor chip and first pads to be pulled down are electrically connected, and an
 power-supply-connecting external wires through which a power supply pad of said semiconductor chip and
 second pads to be pulled up are electrically connected;

wherein said ground-connecting external wire is connected to a ground lead frame, whereas said
 power-supply-connecting external wire is connected to a power supply lead frame.

10. The semiconductor physical quantity sensor according to Claim 9, wherein said ground-connecting
 external wire and said power-supply-connecting external wire are each connected to corresponding lead frames
 outside said resin case

11. The semiconductor physical quantity sensor according to Claims 9^{or} 10, wherein said